Special Issue

Recent Advances in Micro/Millimeter-Wave Imaging Technology

Message from the Guest Editor

Micro/millimeter-wave (MMW) technology has achieved great progress. The performance of vacuum microwave sources, solid-state microwave devices, and microwave integrated circuits (IC) has improved by several orders of magnitude. Those breakthroughs, on high-power source and super sensitive detectors, provide essential technologies for advanced microwave imaging realization. High-speed data acquisition and steaming are established for micro/MMW real-time visualization applications on the sensor industry, defense systems, fusion diagnostics, etc. AI and image neural network learning technology are also high-priority topics in the development of imaging technology. IC technology facilitates combing many bulky microwave components onto single, tiny pieces of the semiconductor substrate. Such a compact SoC can be inexpensively customized for fully optimized instruments. Undeniably, SoC is becoming one of the most important development trends of micro/MMW imaging technology, which provides the ultimate solution for the high integration level, high performance, strong tolerance in the harsh environment, and superior compatibility of the micro/MMW imaging system.

Guest Editor

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Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

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